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TITLE: LACTIC ACID RESIN COMPOSITION AND MOLDING FORM
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ABSTRACT:

PROBLEM TO BE SOLVED: To obtain a composition imparted with adhesion while keeping transparency of a lactic acid resin by containing the lactic acid resin and a specified adhesive.

SOLUTION: A lactic acid resin composition is obtained by compounding 1-100 pts.wt. of an adhesive containing one compound or a mixture of two or more compounds selected from polyester elastomers, polyamide elastomers, rosin derivatives and terpene resins, to 100 pts.wt. of the lactic acid resin composition having 10,000 to 1,000,000 weight-average molecular weight and containing 100 pts.wt. of polylactic acid and 10-100 pts.wt. of at

least one
compound selected from an aliphatic polycarboxylic acid ester, an
aliphatic
polyalcohol and an oxyacid ester. After this lactic acid resin
composition is
molded in forms of a film by meet heating at 100-280°C, the film
having
10-60% of crystallinity is obtained by being elongated 1.5- to 5-fold
in at
least uniaxial direction in a temperature range of the glass
transistor
temperature to the melting point temperature.

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